

## DoD Updates EIT's \$149M PCB Deal

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**ENDICOTT, NY** – The U.S. Department of Defense has awarded **Endicott Interconnect Technologies** a \$148.6 million contract modification to its current program to supply finished assemblies for a high-reliability, high-performance computing application.

Under the deal, EI produces card frame assemblies, including HyperBGA organic semiconductor packaging, multichip module assemblies, PCBs, functionally tested assemblies, and supplies engineering services.

The contract modification period is from May to December this year.